

WP1: Test engineering and Design for Testability of Micro- and Nano-Systems

MEMS Testing through Bias Superposition

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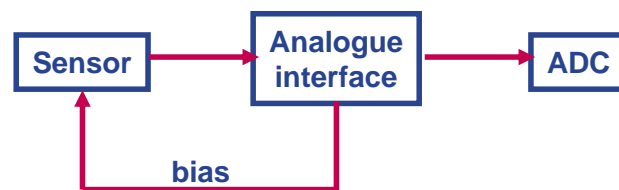
LIRMM, University of Montpellier



«Design for Micro & Nano Manufacture (NoE PATENT-DfMM)»

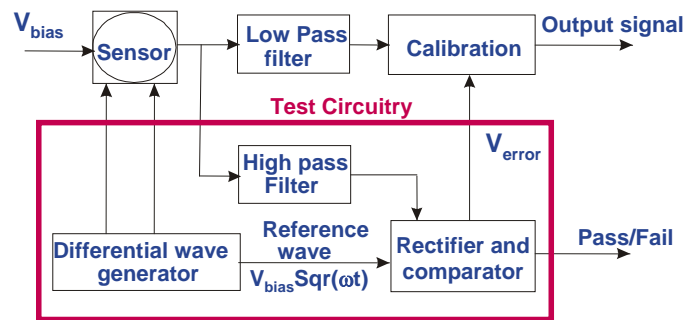
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- Architecture of microsensors



- Solutions for cross-sensitivity compensation, auto-calibration and health monitoring:
 - Triple Modular Redundancy (TMR) ⇒ not competitive
 - Secondary sensor
 - Bias superposition
 - Only one sensor to perform both measurement of the physical parameter and to provide information regarding its transfer function
 - Alteration of the sensor bias outside its operating frequency band
 - Superposition of a signal test
 - Amplitude modulation of the bias to create a signal test

- Test principle and high level diagram of the system:



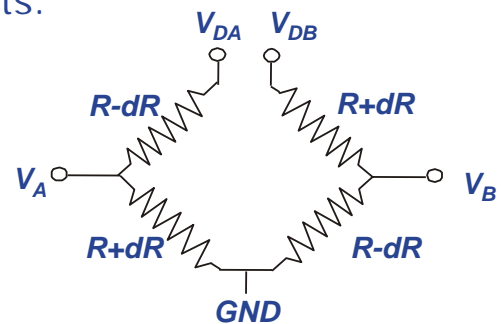
- V_{DD} is split into two differential inputs:

$$V_{DA} = V_{bias} + V_{bias} \text{Sqr}(\omega t) \quad ' \quad V_{DB} = V_{bias} - V_{bias} \text{Sqr}(\omega t)$$

Fault-free sensor

$$V_{outDC} = V_{bias} \frac{dR}{R}$$

$$V_{outAC} = V_{bias} \text{Sqr}(\omega t) \quad \Rightarrow \quad V_{error} = 0$$



- Response of a faulty device:

- DC response

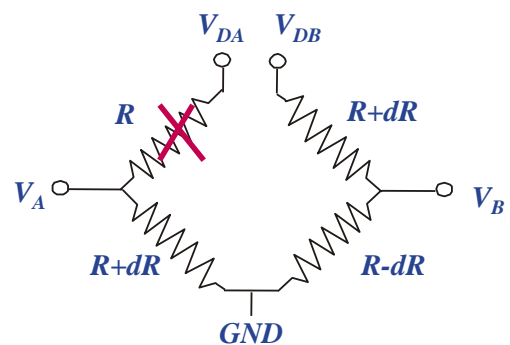
$$V_{outDC} = \left(\frac{3RdR + dR^2}{4R^2 + 2RdR} \right) V_{bias}$$

- Amplitude of the AC response

$$V_{outAC} = \left(\frac{4R^2 + RdR - dR^2}{4R^2 + 2RdR} \right) V_{bias}$$

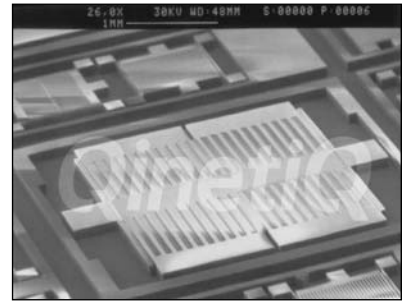
- Error signal: $V_{err} = \left(\frac{RdR + dR^2}{4R^2 + 2RdR} \right) V_{bias}$

- Calibration: $V_{out} = V_{outDC} + V_{err} = \frac{dR}{R} V_{bias}$

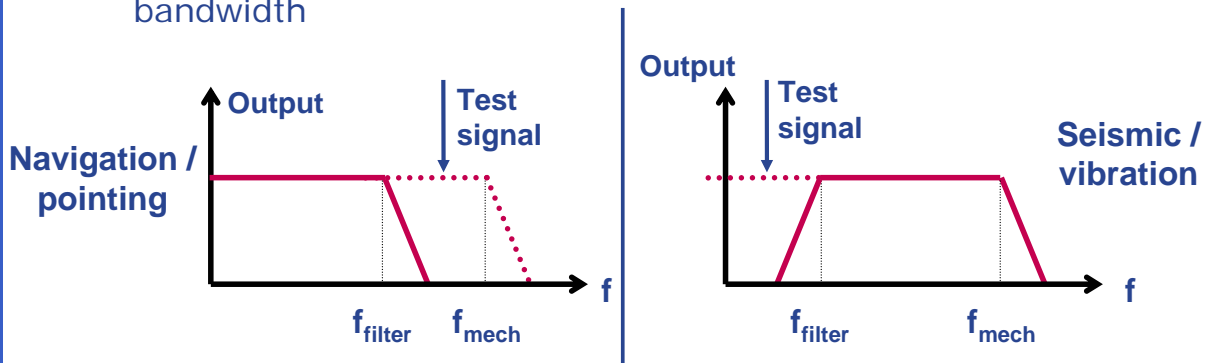


Response of a fault-free device !

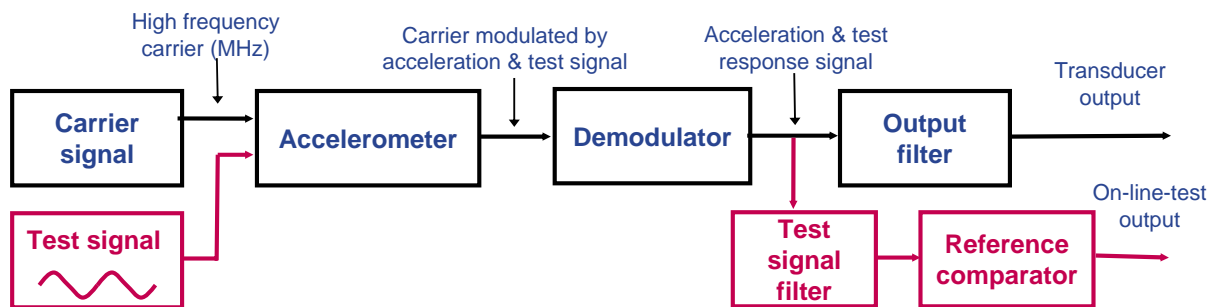
- Potential demonstrator for bias superposition technique
 - Capacitive accelerometer of QinetiQ
 - Signal test below the mechanical cut-off frequency
- Bias superposition frequency depends on application
 - Navigation/pointing applications - requires DC output
 - Seismic/vibration applications - finite bandwidth



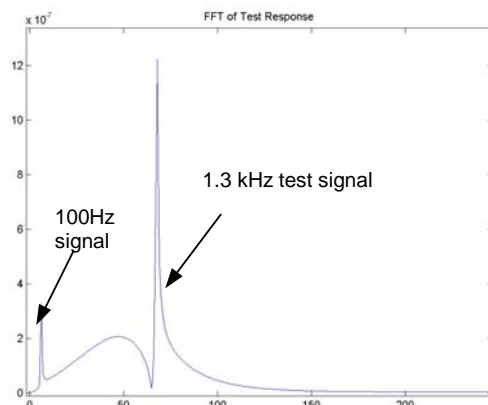
DRIE SOI (100µm thick)
 Accelerometer (2.6mm x 2.6mm)

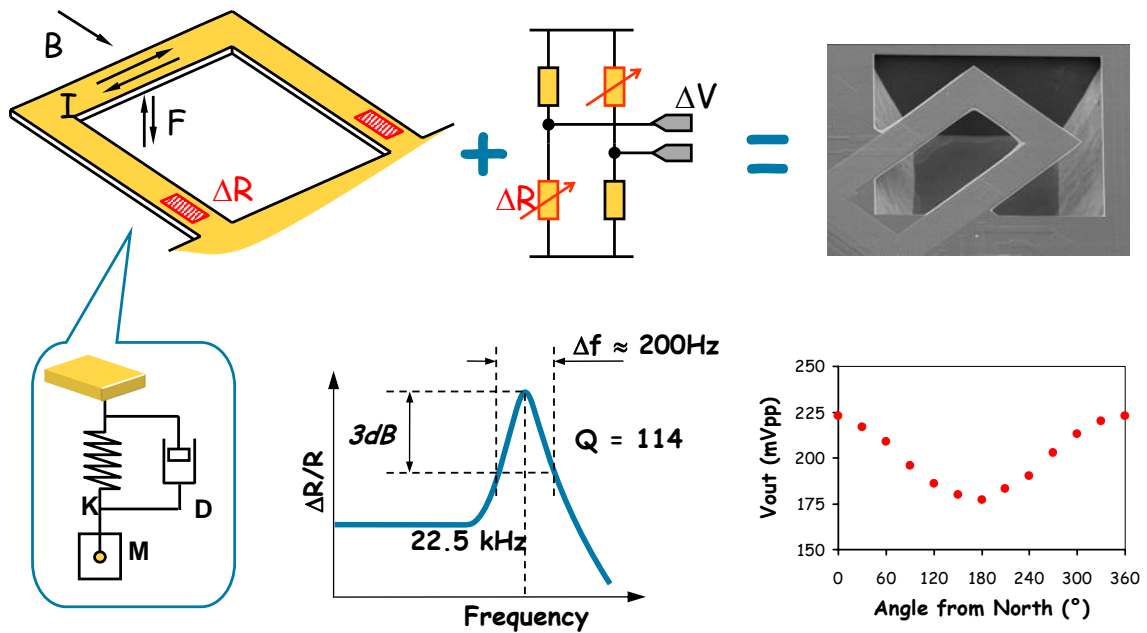


- High level diagram of the system + bias superposition

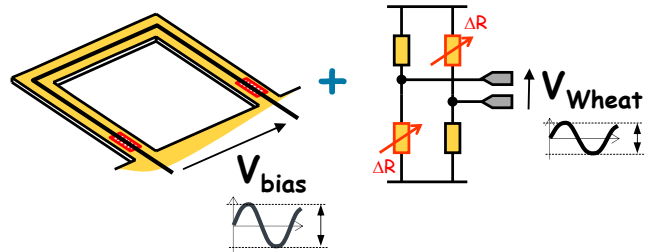


- Matlab simulations
 - Acceleration: 1mg, 100Hz
 - Test signal: 50mg, 1.3kHz

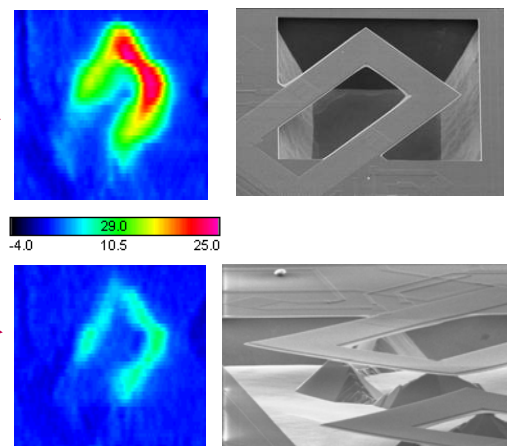
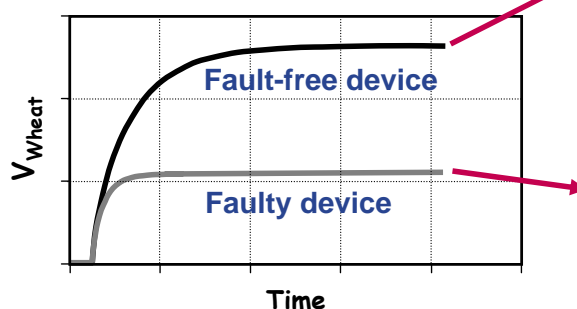


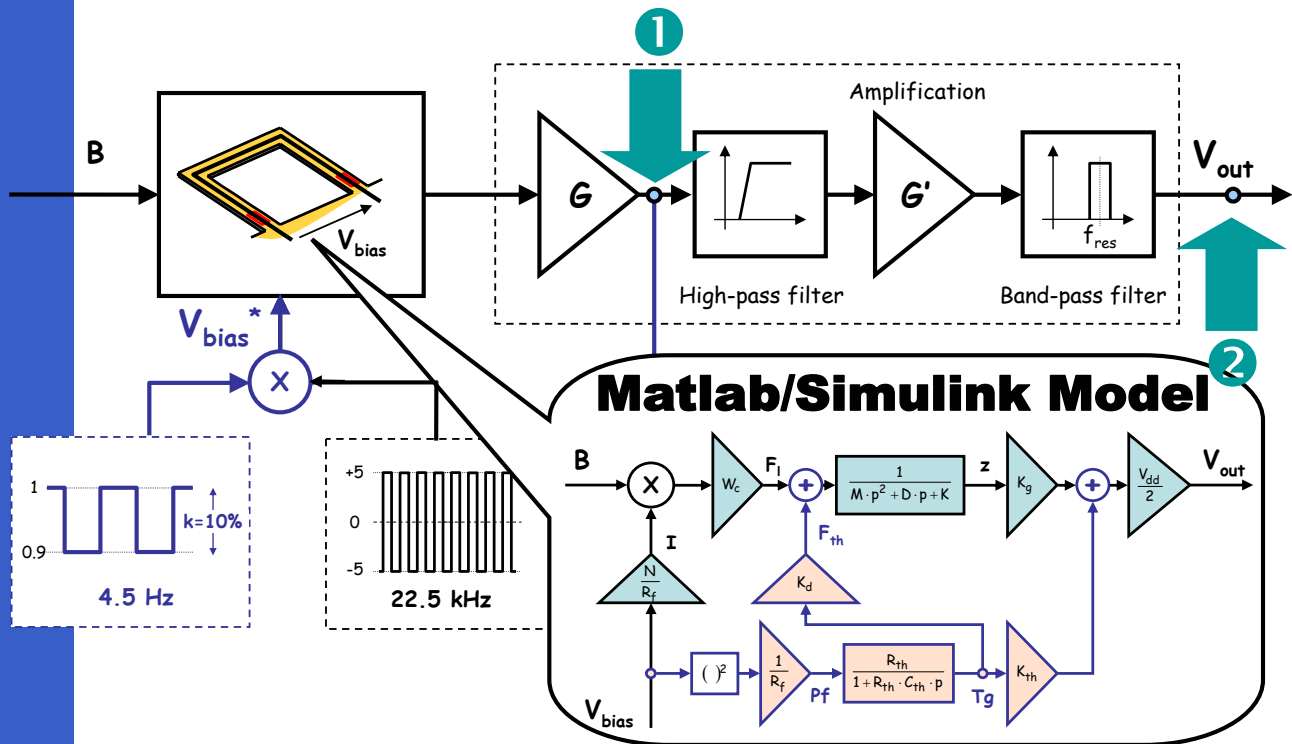


- 2 effects related to temperature
 - Temperature induced signal due to the thermal sensitivity of the gauges
 - Deformation of the mechanical frame due to different thermal expansion coefficient



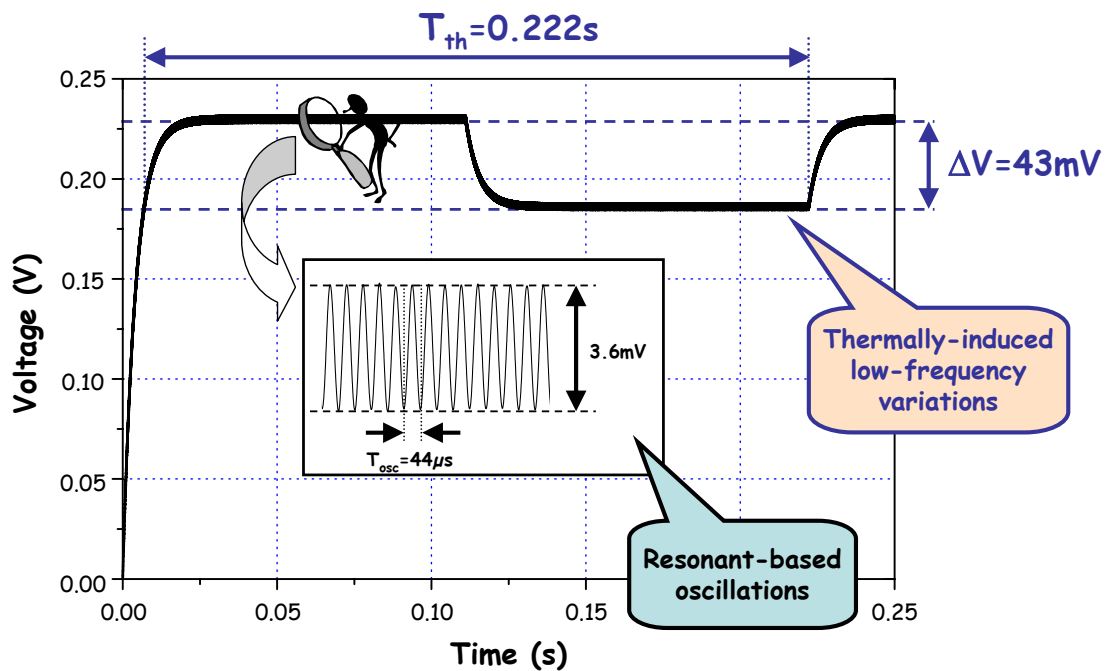
- Test of etching fault





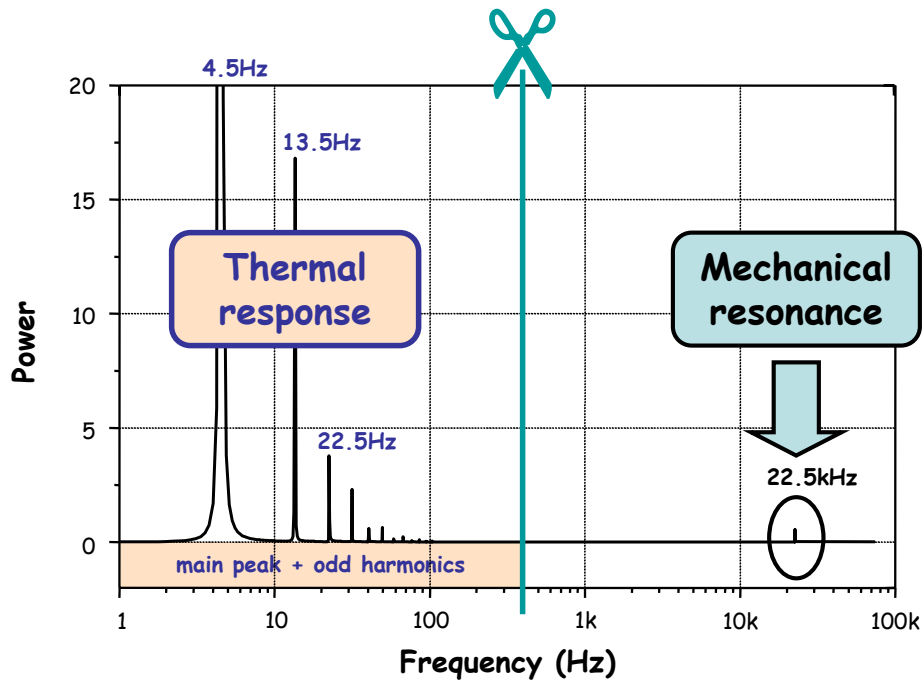
k=10%

Transient response



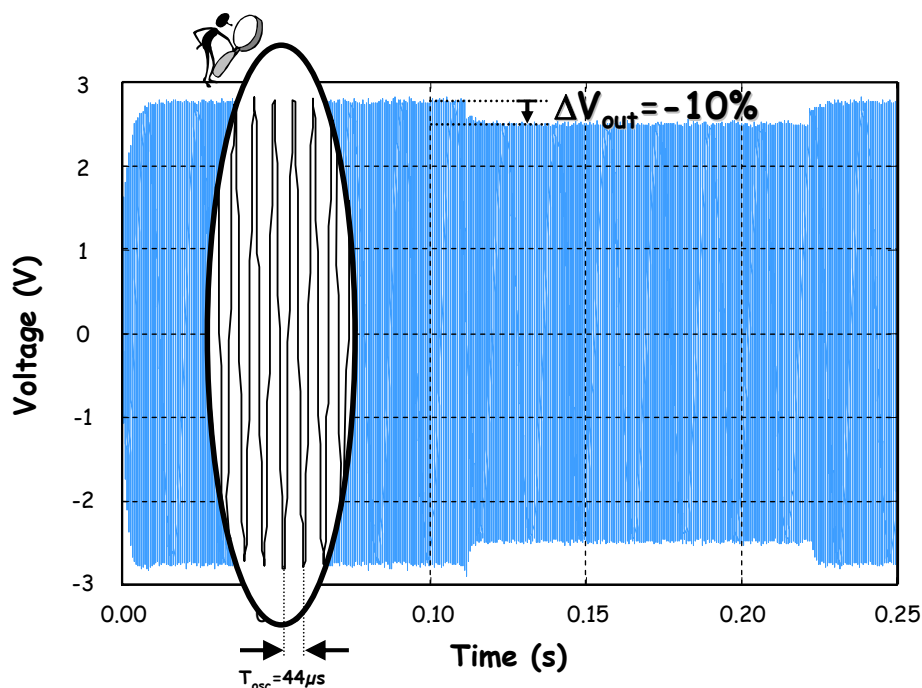
k=10%

Frequency spectrum



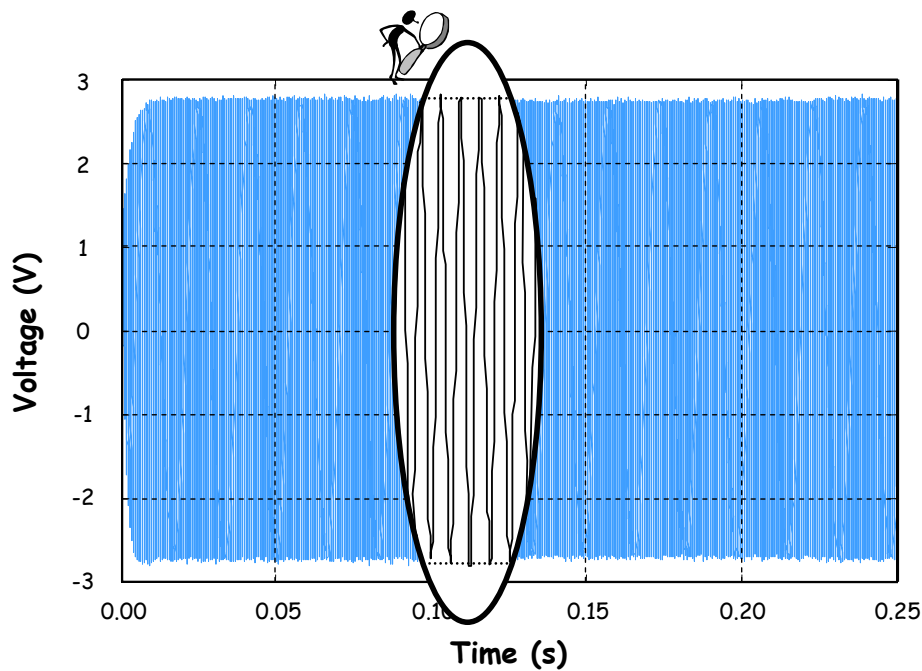
k=10%

Transient response



k=1%

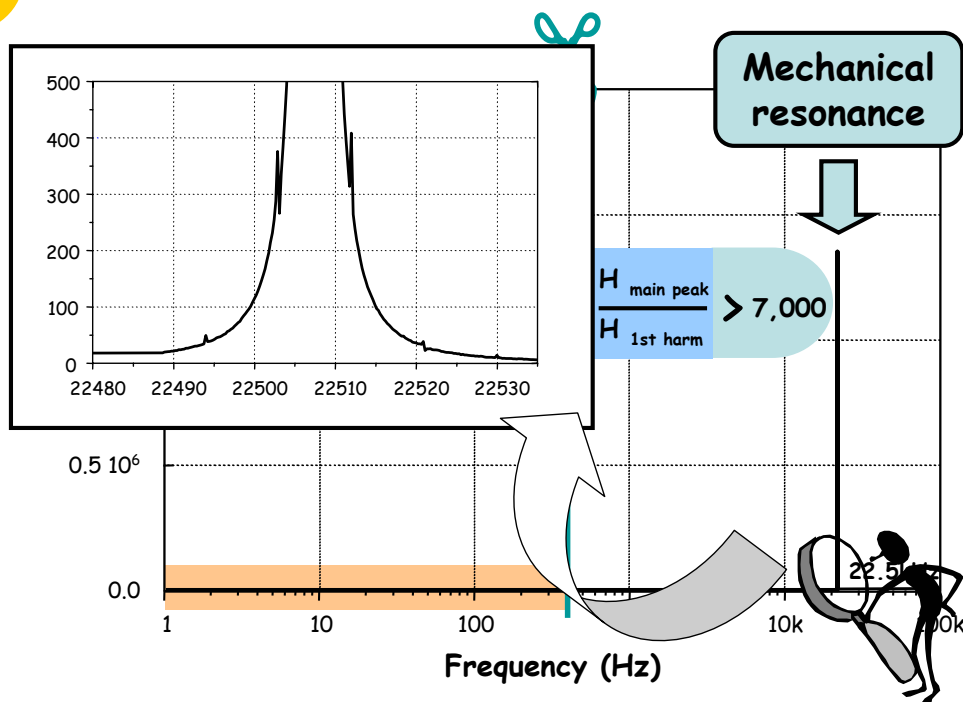
Transient response



k=1%

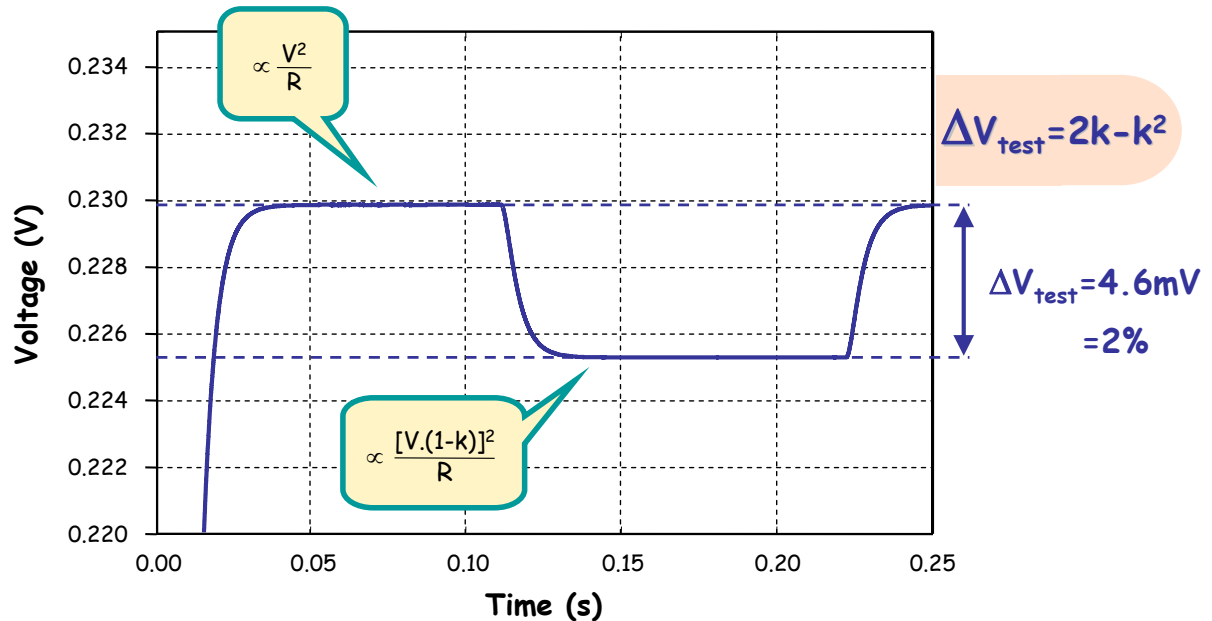
Functional output

Frequency spectrum



k=1%

Transient response



- Evaluation of bias superposition at the system level:
 - Different kind of sensors (capacitive, piezoresistive, ...)
 - several architectures were studied with respect to test setup and response analysis
 - spectrum analysis was used to demonstrate on-line ability
- Extension of the project (2005):
 - Evaluation at the circuit (layout) level: silicon cost, DfT, ...
 - Evaluation of the efficiency with fault modeling, fault coverage
 - Application of Bias superposition to different kind of MEMS